

IN THE CLAIMS

Claims 1-14 (Canceled).

15 (Currently Amended). A method for mounting multiple semiconductor dies on a single leadframe having fingers, comprising:

stacking at least two semiconductor dies having substantially the same rectangular dimensions on top of one another such that one of said dies is mounted on top of the leadframe fingers and the other of said dies is mounted on and in contact with the die mounted on the leadframe fingers, both of said dies being on the same side of said leadframe fingers; and wirebonding each of said semiconductor dies to the same leadframe fingers.

16 (Previously Presented). The method of claim 15, wherein one of said semiconductor dies is mounted back to back on the other of said semiconductor dies.

Claim 17 (Canceled).

18 (Original). The method of claim 15, wherein a first semiconductor die has a lead-on-chip configuration.

19 (Original). The method of claim 15, wherein one of said dies is secured to said leadframe and the other of said dies is secured to the die secured to the leadframe.

20 (Original). The method of claim 15, further comprising wirebonding the semiconductor dies to the leadframe, said dies having facing sides and outwardly facing sides by extending wires to bond pads on the outwardly facing sides of said die.

21 (Currently Amended). A method of connecting multiple semiconductor dies having bonding pads and a single leadframe having lead fingers, comprising:

locating a first semiconductor die on the lead leadframe fingers of the leadframe;

stacking a second semiconductor die on said first semiconductor die and in contact with said first semiconductor die and on the same side of said lead fingers as said first semiconductor die; and

electrically connecting the bonding pads of the semiconductor dies to the same lead fingers of the leadframe.

22 (Original). The method of claim 21, further comprising encapsulating the semiconductor dies and the leadframe in a single package body.

Claims 23-31 (Canceled).

32 (Currently Amended). A method for mounting multiple semiconductor dies on a single leadframe having fingers with first and second sides, comprising:

stacking first and second semiconductor dies having substantially the same rectangular dimensions on top of and in contact with one another;

mounting the first semiconductor die on said first side of said a leadframe finger fingers;

mounting the second semiconductor die on the first side of said leadframe fingers; said first semiconductor die; and

mounting said semiconductor die directly on said first semiconductor die; and

wirebonding the first and second semiconductor dies to the same lead fingers of the leadframe.

Claim 33 (Canceled).

34 (Previously Presented). The method of claim 32 wherein the first semiconductor die is mounted back to back on the second semiconductor die.

Claim 35 (Canceled).